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IVEC 2019

20th International
Vacuum Electronics Conference

April 28 – May 1, 2019
Paradise Hotel Busan, South Korea

Mini Course : April 28
IVEC 2019 : April 29 – May 1



General Chair

Gun-Sik Park (Seoul National University)

Program Co-Chairs

Jin Joo Choi (Kwangwoon University)
EunMi Choi (Ulsan National Institute of Science and Technology)

IVEC2019 QR Code





Important Dates * Important dates can be changed.

- First call for papers** June 11, 2018
- Abstract submission deadline** December 21, 2018
- Notification of acceptance** January 25, 2019
- IEEE compliant abstract due** February 22, 2019
- Advance registration ends** March 31, 2019

Technical Subject Categories

1. Vacuum Electron Devices

- Traveling-wave tubes (all types)
- Crossed-field devices (oscillators and amplifiers)
- Klystrons
- Multiple-beam devices
- Inductive output tubes
- Fast-wave devices (gyrotrons, gyro-amplifiers)
- Free electron lasers and masers
- Pulse compression devices
- Plasma filled amplifiers and oscillators
- High power microwave devices / RF directed energy
- Triodes, tetrodes and pentodes
- Power switches

2. Vacuum Microelectronics / Nanoelectronics

- Microwave, millimeter-wave & THz amplifiers and oscillators
- Field emitter arrays
- Flat panel displays
- Sensors and detectors

3. Systems and Subsystems

- Microwave and millimeter-wave power modules
- Electronic power conditioners, modulators, and supplies
- Linearizers
- Amplifier/antenna coupling
- Power combining system
- Device and system integration
- Reliability

4. Technologies

- Cathodes and other electron emitters
- Component parts (e.g. guns, circuits, windows, collectors)
- Analysis and computer modeling
- Micro-fabrication techniques (e.g. LIGA, DRIE, 3-D printing, CNC)
- Novel materials (e.g. dielectrics, coatings, magnetic materials)
- Electron emission
- RF breakdown
- Linearity, intermodulation and noise
- Novel measurement techniques
- Miniaturization
- Thermal power management and control

5. Applications of Vacuum Electron Devices

- Defense
- Radar
- Telecommunications
- Medicine
- Particle accelerators
- Nuclear fusion
- Plasma
- RF interference
- Instruments and lithography
- Materials processing
- Television
- Displays
- Electric propulsion

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